

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2865581

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MARTIN BECKER	03/19/2014
RONALD EISELE	03/19/2014
FRANK OSTERWALD	03/17/2014
JACEK RUDZKI	03/21/2014
RECEIVING PARTY DATA	
Name:	DANFOSS SILICON POWER GMBH
Street Address:	HUSUMER STRASSE 251
City:	FLENSBURG
State/Country:	GERMANY
Postal Code:	DE 24941
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14348356
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DATE SIGNED:	05/21/2014
Total Attachments: 2	
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ASSIGNMENT

THIS INSTRUMENT OF ASSIGNMENT WITNESSETH THAT:

WHEREAS, we,

Martin Becker of Franckstrasse 6, Kiel, DE 24118 Germany
Ronald Eisele of Faulstrasse 21, Surendorf, DE 24229 Germany
Frank Osterwald of Jakobsleiter 7, Kiel, DE 24159 Germany
Jacek Rudzki of Steinberg 38, Kiel, DE 24107 Germany

respectively, have invented improvements in

METHOD FOR CREATING A CONNECTION BETWEEN METALLIC MOULDED BODIES AND A POWER SEMICONDUCTOR WHICH IS USED TO BOND TO THICK WIRES OR STRIPS

for which we have executed on even date herewith an application for Letters Patent of the United States, and

WHEREAS, Danfoss Silicon Power GmbH, a corporation of Germany, having a place of business at Husumer Strasse 251, Flensburg, Germany, DE 24941 is desirous of acquiring an interest in said invention, said application and the Letters Patent to be issued therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for and in consideration of the sum of ONE DOLLAR to each in hand paid and other good and valuable consideration, the receipt whereof is hereby acknowledged, we have sold, assigned and set over, and do hereby sell, assign and set over to said corporation, its successors or assigns, the entire right, title and interest to and in said invention in the United States and in all countries foreign to the United States, said United States application for Letters Patent therefor and all divisionals, continuations, reissues, reexaminations and extensions thereof, and the Letters Patent when issued; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue the Letters Patent based upon said application(s) to said corporation as the assignees of our entire right, title and interest to and in the same, for the sole use and behoof of said corporation, its successors or assigns.

And we also hereby covenant and agree to sign all proper papers including other applications for patents and assignments thereof in the United States and application for patents and assignments in all foreign countries, and to execute all rightful oaths and to take any other proper action that may in the judgment of the

said corporation be necessary for securing thereto full rights to said invention, all of the foregoing to be at the expense of said corporation.

IN TESTIMONY WHEREOF, I have hereunto set my hand this

19 day of March, 2014.

M. Becker
Martin Becker

IN TESTIMONY WHEREOF, I have hereunto set my hand this

19 day of March, 2014.

R. Eisele
Ronald Eisele

IN TESTIMONY WHEREOF, I have hereunto set my hand this

17 day of March, 2014.

F. Osterwald
Frank Osterwald

IN TESTIMONY WHEREOF, I have hereunto set my hand this

21 day of March, 2014.

J. Rudzki
Jacek Rudzki